Electronics Manufacturing & Packaging Symposium

06-Oct Professional Development Courses

09:00		registration	
10:00	PDC 1	ESA, Olivier Perat, Swarnajyoti Mukherjee, Denis Lacombe	Working with ESA: Advancing EEE Sovereignty, Standards, and Innovation
11:00		break	
11:30	PDC 2	Alter Technology, Nieves García Alcaide	Trends in Microelectronic Packaging and Testing
13:00		lunch	
14:00	PDC 3	Spacechips, Rajan Bedi	Flexible PCB Design and Manufacturing for Space Applications
15:00		break	
15:20	PDC 4	Spacechips, Rajan Bedi	Right-First-Time Design for Fabrication and Assembly Considerations When Manufacturing Space-Grade PCBs
16:20		break	
16:40	PDC 5	ESA, Gianni Corocher, Carlons Sanchez Herrera, Stan Heltzel	Space mission classification and the materials & processes control board
17:40		end	

7-9 Oct Exhibitors

stand 1	ACB NV, Jan De Maeyer	stand 9	ELEMCA, Clovis Lataste
stand 2	CERcuits BV, Frederik Luppens	stand 10	Fraunhofer EMFT, Frank Ansorge
stand 3	Cistelaier S.p.A., Federica Sala	stand 11	SERMA Microelectronics, Constantin De Guerry
stand 4	Ncab Group, Sander Maasman	stand 12	AEMtec GmbH, Rena Vignold
stand 5	Oki Circuit Technology Co., Ltd., Ogura TOSHIHIKO	stand 13	Isocom, Arash Robin Tahmosybayat
stand 6	Würth Elektronik GmbH & Co. KG, Christine Stegmeier	stand 14	Taipro Engineering, Thibault Lioret
stand 7	Specialty Coating Systems, Laurent Dardier	stand 15	Glenair GmbH, Martin Eichelberger
stand 8	Jaltek, Chris Day		

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08:00		registration		
08:45		welcome	ESA, Stephane Mespoulet	Welcome
09:00			Global Electronics Association, Peter Tranitz	The path towards Advanced Electronic Packaging
09:20	1	additive manufactured electronics	HTV Conservation GmbH, Thorsten Leist	Quality assurance of additively manufactured electronics
09:45	2		Politecnico di Milano, Andrea Mistrini	Laser Additive Manufacturing of High-Performance Thermal Management Systems for Aerospace High-Power Electronics
10:10	3		Holst Centre - Tno, Darragh Walsh	Novel Additive Manufacturing Platform for Freeform 3D Microelectronics and Packaging
10:35	4		Jadavpur University, o.b.o. Soham Ghosh	Design of Scalp-Implantable and Non-Invasive Antenna System for Intracranial Pressure Monitoring
11:00		break		
11:30	5	PCB 1	Alter Technology, Dimas Morilla Mairen	Critical Role of Tg and CTE Characterization in PCB Design Using Thermomechanical Analysis (TMA)
11:55	6		Hytek, Poul Juul	Physical characterization of PCB materials
12:20	7		Istituto Italiano Della Saldatura, Luca Moliterni	Study of Base Laminates Used for High Reliability Printed Circuits Boards
12:45	8		LPKF Laser & Electronics, Patrick Stockbrügger	Potential of laser depaneling for harsh environments in terms of quality and reliability
13:10		lunch		
14:10	9	lead-free assembly	Nanospace, Philippe Hersberger	Lead-free assembly technologies for telecom satellite equipment (ESA ARTES)
14:35	10		Technical University of Darmstadt, Guillaume Meyer	Lead-Free Transition for the European Space Sector - the Tin Whiskers Challenge
15:00	11		Spur Electron, Cathy Chandler	Lead-free assembly technologies for telecom satellite equipment
15:25	12		Teledyne E2v, Eric Perriaud	Board Level Reliability Testing of BGA Packages Equipped with Lead-Free Interconnection Solutions and Dedicated to Space Applications
15:50		break		
16:20	13	modelling	Hooke Electronics, Jean-Baptiste Libot	Physics-of-Failure Based Reliability Modeling of Lead-Free Electronic Assemblies Under Thermal Cycling
16:45	14		Imec, Klara Volckaert	Experimental Data-Driven Prediction of Input Parameters for Finite Element Simulations for Electronic Assemblies
17:10	15		Elastic-Simulations Gmbh, Harald Ziegelwanger	Modelling the reliability of through-hole-technology assemblies
17:35		end		
18:00		welcome reception at Space EXPO		
20:00		end		

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09:00	16	assembly	Thales Alenia Space, Hugo Garcia o.b.o. Paula Marin Banque	Low loss PCB solutions - focus on nickel-free finishes
09:25	17		Lilotree, Kunal Shah	Novel Surface Finish for High frequency PCB Technologies- How to Achieve Optimum Signal Integrity & Reliability.
09:50	18		Thales Alenia Space Italia, Andres Matias Dabas	Qualification of high-speed press-fit connectors for space applications
10:15	19		Thales Alenia Space, Hugo Garcia	Evaluation of Pressfit Technology for High-Reliability Space Applications
10:40	20		OHB System, Alexander Hannes	Microcoil Springs – an alternative to CCGA tin columns
11:05		**break**		
11:35	21	EEE packaging 1	Ncab Group, Jan Pedersen	The PCB Journey from Multilayer to Ultra HDI
12:00	22		Alter Technology, Mari Carmen López	High Temperature Lead Free Solder for Internal Soldering of EEE Parts: Manufacturing and Testing
12:25	23		Alter Technology, Luis Alejandro Arriaga Arellano	Space Radiation shielding in microelectronics through the development of advanced composite Materials (SRPROTEC Project)
12:50	24		Ghent University / Imec, Geert Van Steenberge	Wafer-Scale Packaging of Photonic Switches and Transceivers
13:15		**lunch**		
14:15	25	PCB 2	ACB, Joachim Verhegge	High-speed HDI technology for space applications: a road to qualification
14:40	26		Oki Circuit Technology, Ogura Toshihiko	Development of HDI PCBs using low-loss materials
15:05	27		Cistelaier, Luca Pagnani	Approaching New Challenges: How We Got to Space"
15:30	28		Ilfa Gmbh, Nikita Jacobs	Copper-Based Sinter Paste Integration for Advanced PCB Packaging and Multiboard Architectures
15:55		**break**		
16:25	29	microvias	Elemca, Jeremie Dhennin	EBSD Evaluation of the Impact of Reflow Temperature on Microvia Microstructure
16:50	30		Imec, Maarten Cauwe	Microvia manufacturing capability assessment: a perspective on three levels of stacked microvias
17:15	31		Imec, Chinmay Nawghane	Optimizing Multilevel Microvia Structures for Thermo-Mechanical Reliability in High-Speed HDI PCBs
17:40		**end**		
19:30		Dinner Noordwijk Zeemeeuw.com		
23:00		**end**		

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09:00	32	assembly & modelling	Istituto Italiano Della Saldatura, Stefano Barbiere	The Surface Insulation Resistance (SIR) test according to ECSS-Q-ST-70-61 and IPC-TM-650 2.6.3.7 for flux residues study
09:25	33		PBT Works, Vladimir Sítko	Cleaning of electronic assembly: development and qualification using the Glass Test board
09:50	34		Elemca, Jeremie Dhennin	Finite Element Modeling of SAC305 Solder Joint Reliability under Thermomechanical Cycling for Space Applications
10:15	35		Thales Alenia Space Belgium, Vincent Voet	Thermomechanical fatigue lifetime prediction of solder joints in electronic component assemblies
10:40		**break**		
11:10	36	EEE packaging 2	AEMtec, Robin Jerratsch	Status on GSTP "Definition and validation of an European source of FC Bump services for 28nm and lower technology nodes"
11:35	37		Tno Defence, Safety And Security, Tindara Verduci	Advanced packaging technologies for next generation integrated RF systems
12:00	38		Thales Alenia Space Italia, Andres Matias Dabas	Advanced Digital Processor System-in-Package (SiP) for space applications
12:25	39		Thales Alenia Space Italia, Mirko Rocci	Advanced uHDI and Embedded-Power SiP Technology for Space Applications
12:50	40		Fraunhofer Izm, Tekfouy Lim	Advanced system integration technologies for Space applications
13:15		**lunch**		
14:15	41	assembly testing	ESA, Jordi Oller Sánchez	CT Scan as a Non-Destructive Alternative to Microsectioning for Electronic Assembly Verification
14:40	42		Jtag Technologies, Peter van den Eijnden	TapSpacer: remote access to embedded JTAG boundary-scan logic
15:05	43		Airbus Defence And Space, Asensio Zapata	Asymmetric test cycling as a new approach for validation of electronic assemblies in harsh environment
15:30	44		DSI Aerospace, Jan Frederik Wagenfeld	PCB Design Challenges in Next-Generation Space Mass Memory Units
15:55		closing	ESA, GEA	
16:05		**end**		